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PATENT ABSTRACTS OF JAPAN

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(71) Applicant: OLYMPUS OPTICAL CO

(72) Inventor: SAITO HIDETOSHI

(74) Representative:

(54) ELECTRONIC ENDOSCOPE

(57) Abstract:

PROBLEM TO BE SOLVED: To provide an electronic endoscope which prevents the occurrence of trouble, such as peeling, in a joint part, etc., even when autoclave sterilization is repetitively carried out.

SOLUTION: Adhesives are respectively separately applied to the respective parts of a solid-state image pickup element 13, ceramic substrates 19 and 20 and a coated fiber 30 with an insulation tube 31 and thereafter, the solid-state image pickup element 13, the ceramic substrates 19 and 20 and the coated fiber 30 with the insulation tube 31 are coated with the adhesives or packing materials, etc., which are resin members, by which resin layers A are disposed and the solid-state image pickup element 13, the ceramic substrates 19 and 29 and the coated fiber 30 are sealed. At this time, the adhesives constituting the resin layers A are in the state that the adhesives are not adhered at all to a shielding frame 22, cable fixing frame 23, image pickup frame 14 and field lens 15 arranged to cover the solid-state image pickup element 13, the first ceramic substrate 19, the second ceramic substrate 20 and the coated fiber 30 or the state that the adhesives partly adhere thereto.

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